# PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|---|---|
| Yu-Wen Liu | 03/22/2011 |
| Ching-Jung Yang | 03/22/2011 |
| Hsien-Wei Chen | 03/22/2011 |
| Hsin-Yu Pan | 03/22/2011 |
| Chao-Wen Shih | 03/22/2011 |

RECEIVING PARTY DATA

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|---|---|
| Name: | Taiwan Semiconductor Manufacturing Company, Ltd. |
| Street Address: | No. 8, Li-Hsin Rd. 6 |
| Internal Address: | Science-Based Industrial Park |
| City: | Hsin-Chu |
| State/Country: | TAIWAN |
| Postal Code: | 300-77 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---|---|
| Application Number: | 13050125 |

CORRESPONDENCE DATA

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|---|---|
| ATTORNEY DOCKET NUMBER: | 2010-0910/24061.1668 |

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| NAME OF SUBMITTER: | David M. O'Dell |
| Total Attachments: 3<br>source=1668Aassignment#page1.tif<br>source=1668Aassignment#page2.tif<br>source=1668Aassignment#page3.tif | |

Docket No.: 2010-0910 / 24061.1668
Customer No.: 42717

# ASSIGNMENT

WHEREAS, we,

(1) Yu-Wen Liu of 4F., No.6, Alley 24, Lane 251, Sec. 5, Nanjing E. Rd.
Songshan District, Taipei City 105, Taiwan, R.O.C.

(2) Ching-Jung Yang of No.2, Aly. 1, Ln. 37, Ziqiang St.
Pingzhen City, Taoyuan County 324, Taiwan, R.O.C.

(3) Hsien-Wei Chen of No. 57, sueitang Street
Sinying City, Tainan County 730, Taiwan, R.O.C.

(4) Hsin-Yu Pan of 3F, No. 23, Lane 1, Sec. 4, Cheng-Teg Road
Taipei, Taiwan, R.O.C.

(5) Chao-Wen Shih of 7F, No. 6, Lane 16, Wenhua Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

have invented certain improvements in

## REINFORCEMENT STRUCTURE FOR FLIP-CHIP PACKAGING

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
___x___ filed on March 17, 2011 and assigned application number 13/050,125 ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Yu-Wen Liu

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Songshan District, Taipei City 105, Taiwan, R.O.C.

Dated: 2011, 3, 22

Yu-Wen Liu
Inventor Signature

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Inventor Name: Ching-Jung Yang

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Pingzhen City, Taoyuan County 324, Taiwan, R.O.C.

Dated: 2011.3.22

Ching-Jung Yang
Inventor Signature

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Inventor Name: Hsien-Wei Chen

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Dated: 2011, 3.22

Hsien-Wei Chen
Inventor Signature

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Dated: 3/22/2011

Inventor Signature

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Dated: 2011.3.22

Chao-Wen Shih
Inventor Signature

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